



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model
[List multiple models if applicable.]

HP A9512 Switch Chassis (JC125B)

HP A8812 Router Chassis (JC150B)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	12
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		2
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		5
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0
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2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2 #

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 2, and then remove mounting angle 2 from the chassis.
2. Remove plastic panel 3 from the chassis.
3. Unscrew the screws on front panel 4, and then remove front panel 4 from the chassis.
4. Unscrew the screws on front panel 5, and then remove front panel 5 from the chassis.
5. Unscrew the screws on blank filler panel 6, and then remove blank filler panel 6 from the chassis.
6. Remove film 7 from the chassis
7. Unscrew the screws on power module 8, and then remove power module 8 from the chassis.
8. Remove film 9 from the chassis
9. Unscrew the screws on blank poe module panel 10, and then remove blank poe module panel 10 from the chassis.
10. Unscrew the screws on blank power module panel 11, and then remove blank power module panel 11 from the chassis.
11. Unscrew the screws on fan frame 12, and then remove fan frame 12 from the chassis.
12. Unscrew the screws on rear cover 13, and then remove rear cover 13 from the chassis.
13. Unscrew the screws on rib 14, and then remove rib 14 from the chassis.
14. Unscrew the screws on PCB 15, and then remove PCB 15.
15. Unscrew the screws on PCB 16, and then remove PCB 16.
16. Unscrew the screws on wire channel 2-2, and then remove wire channel 2-2 from mounting angle 2-1.
17. Unscrew the screws on pcb 4-2, and then remove pcb 4-2 from front panel 4-1.
18. Unscrew the screws on pcb 4-3, and then remove pcb 4-3 from front panel 4-1.
19. Unscrew the screws on pcb 4-4, and then remove pcb 4-4 from front panel 4-1.
20. Unscrew the screws on pcb 4-5, and then remove pcb 4-4 from front panel 4-1.
21. Remove shielding finger 4-6 from front panel 4-1
22. Remove film 4-7 from front panel 4-1.
23. Unscrew the screws on pcb 5-2, and then remove pcb 5-2 from front panel 5-1.
24. Unscrew the screws on pcb 5-3, and then remove pcb 5-3 from front panel 5-1
25. Unscrew the screws on pcb 5-4, and then remove pcb 5-4 from front panel 5-1.
26. Remove shielding finger 5-5 from front panel 5-1.
27. Remove film 5-6 from front panel 5-1.
28. Remove shielding finger 6-2 from front panel 6-1.
29. Remove film 6-3 from front panel 6-1.
30. Remove plastic panel 10-1.
31. Unscrew the screw on plastic panel 10-2, and then remove plastic panel 10-2 from frame 10-3.
32. Unscrew the screws on plastic panel 11-1, and then remove plastic panel 11-1 from panel 11-2.
33. Remove film 12-2 from fan frame 12-1.
34. Remove shielding finger 12-3 from fan frame 12-1.
35. Unscrew the screws on PCB 12-4, and then remove PCB 12-4 from fan frame 12-1.
36. Unscrew the screws on fan 12-5, and then remove fan 13-5 from fan frame 12-1.
- 37.

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3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

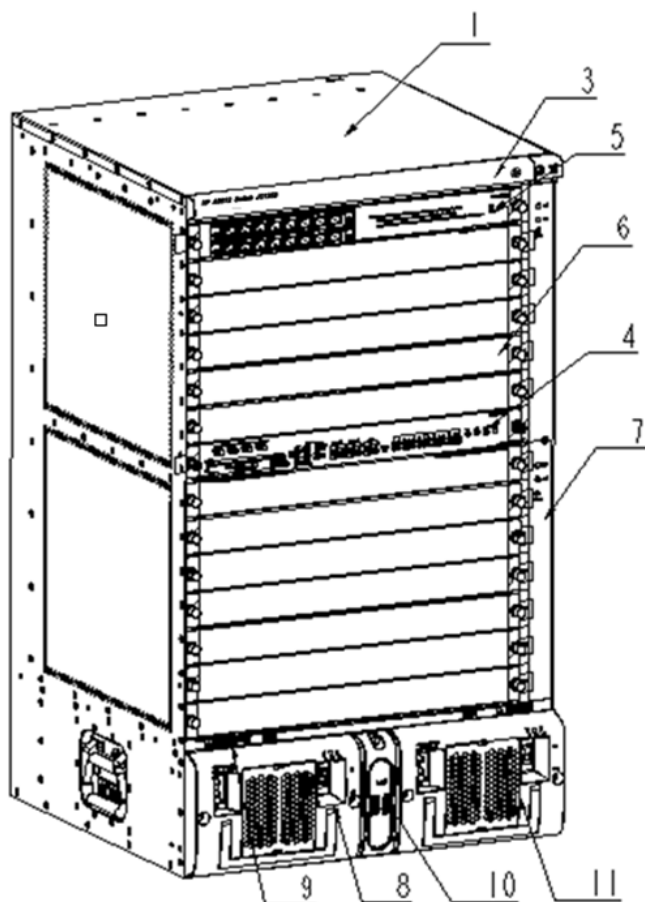


Figure 1 Treatments to the product (front view)

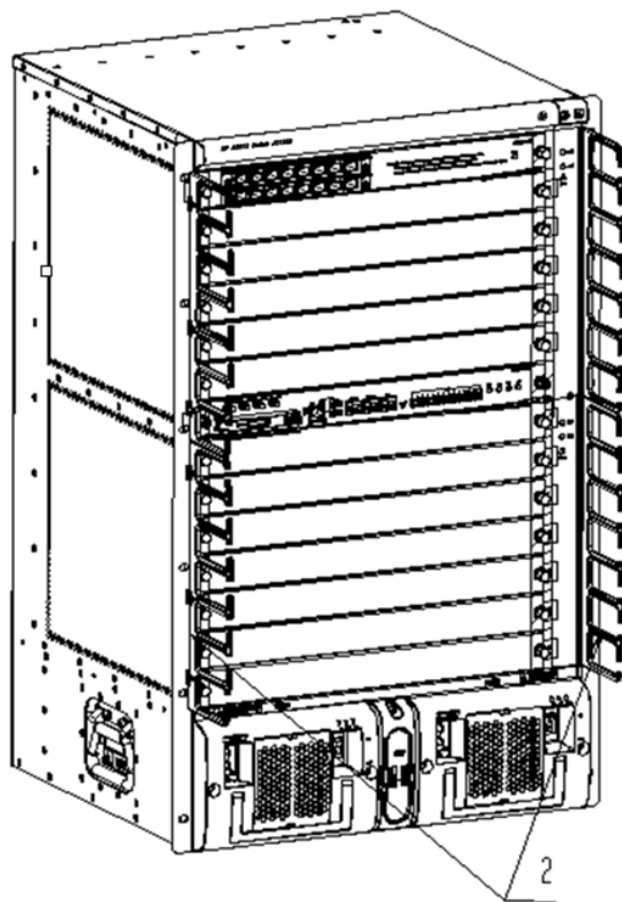


Figure 2 Remove mounting angle

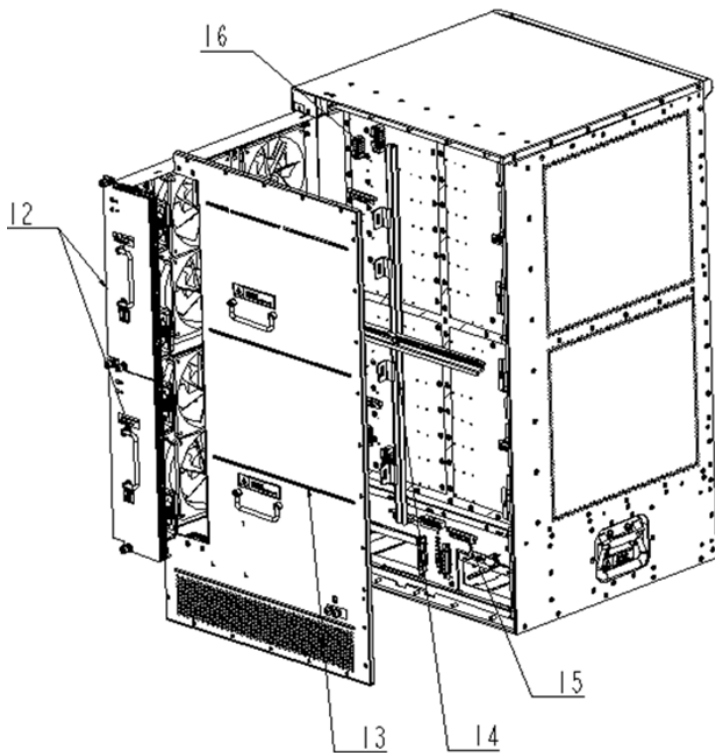


Figure 3 Treatments to the product (rear view)

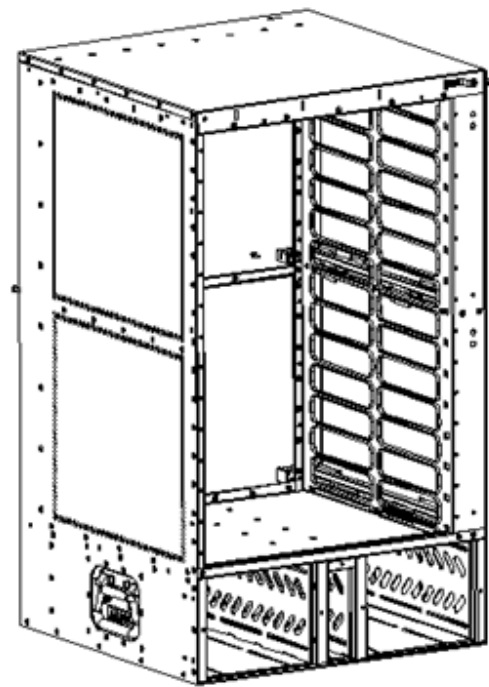


Figure 4 Part 1

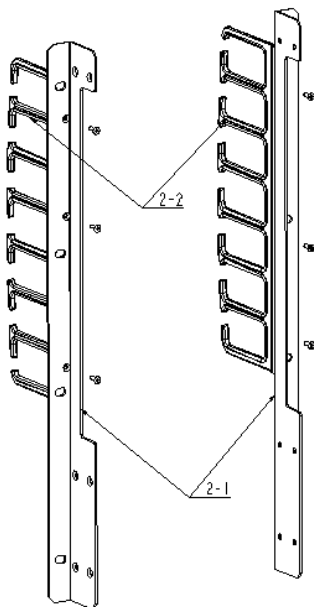


Figure 5 Treatments to mounting angle 2

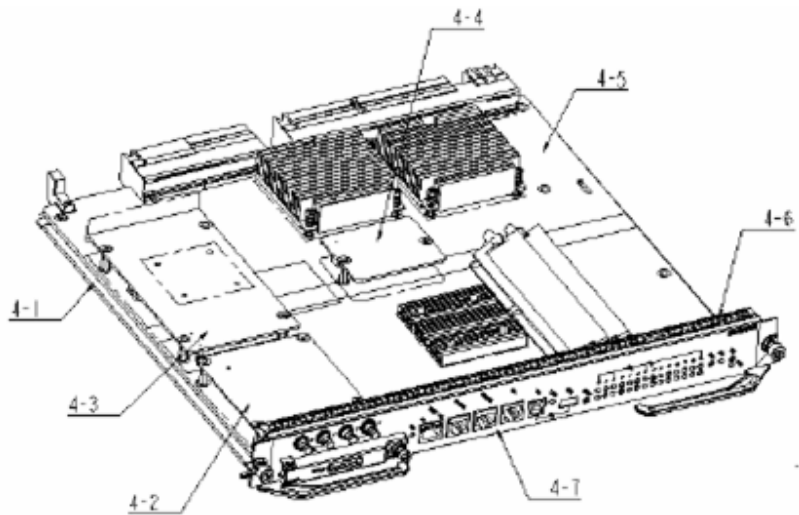


Figure 6 Treatments to front panel 4

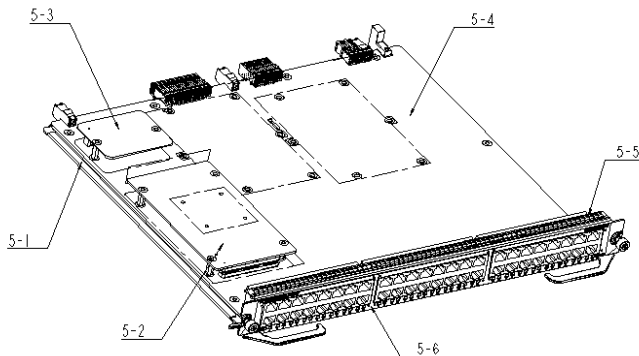


Figure 7 Treatments to front panel 5

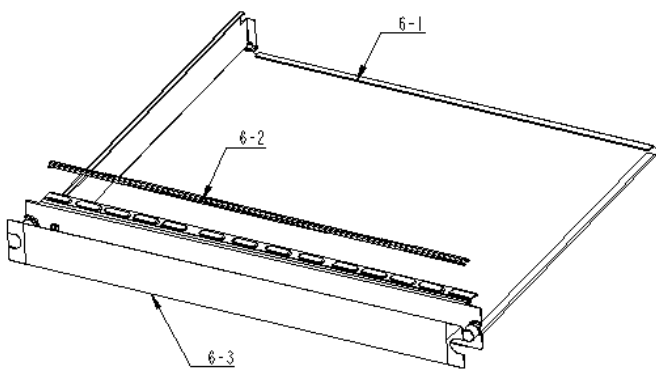


Figure 8 Treatments to blank filler panel 6

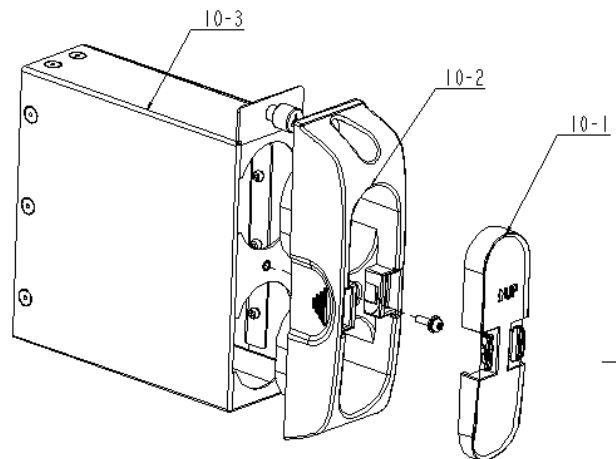


Figure 9 Treatments to blank poe module panel 10

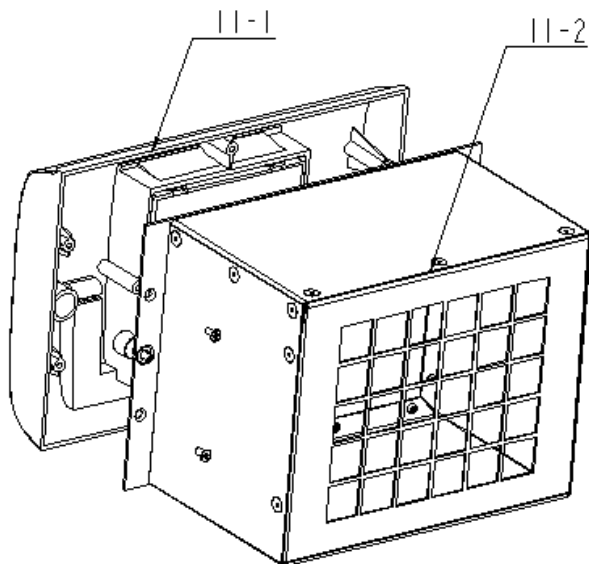


Figure 10 Treatments to blank power module panel 11

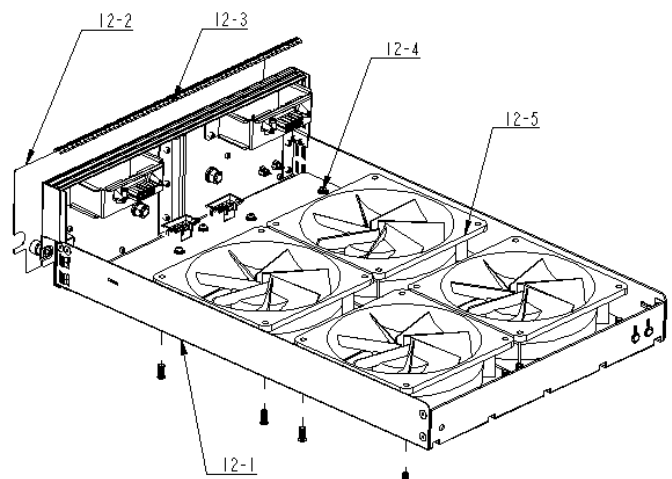


Figure 11 Treatments to fan frame 12

